

Sensors and Materials

Special Issue on Advanced Sensor Materials, Processes, and Applications

Call for Papers

This special issue delves into cutting-edge advancements in sensor materials, processes, and their broad applications, focusing on aerospace, intelligent manufacturing, and the Internet of Things (IoT). We explore various sensors—including those measuring strength, distance, height, and pressure—integral to daily and industrial activities. The scope of this issue encompasses novel materials such as carbon, metals, ceramics, polymers, and their composites, as well as the systems, design strategies, and manufacturing techniques employed. We invite contributions that discuss the applications of innovative biomolecular materials, microorganisms, and a diverse range of organic and inorganic substances in sensor technology, aiming to push the boundaries of how these devices can enhance various aspects of modern life.

Scope:

Sensor design	Sensors in life
Sensor materials	Sensors in manufacturing
Sensor applications	Sensors in IoT
Sensor fabrication	Sensors in systems
Intelligent sensors	Sensors in biomedicine

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If you have any questions, please feel free to contact the editorial staff at the address below.

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